ABSTRACT

APPARATUS AND PROCESS FOR MOLDING WITH REDUCED CULL FORMATION

An apparatus and process are provided for molding electronic devices in a mold, which apparatus comprises at least one runner in the mold connected to a mold supply pot for channeling a molding compound from the mold supply pot to the electronic devices. A plunger assembly is also provided that comprises a main body, and a supplementary body configured to be movable relative to the main body. The plunger assembly is locatable in the mold supply pot and is drivable in a direction towards the runner for forcing the molding compound into the runner. In order to avoid or reduce cull formation, a width of the runner at an opening connecting the runner to the mold supply pot is smaller than a width of the main body of the plunger assembly.

(FIG. 8)